

10/033217
12/28/01

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10033217	FILING DATE 12/28/2001	CLASS 475 264	SUBCLASS 547	GAU 1732 4732	EXAMINER Heitbrink Tim
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**CONTINUING DATA VERIFIED: none

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** FOREIGN APPLICATIONS VERIFIED:

JAPAN 2001-009119 01/17/2001

JAPAN 2001-009120 01/17/2001

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no

35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

WAKA 19.305

TITLE : Mold device for injection molding of synthetic resin

U.S. DEPT. OF COM. / PAT. & TM. PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawg.	Figs. Drawg.
			Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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